

	Type	L #	Hits	Search Text	DBs	Time Stamp
1	BRS	L1	126767 7	semiconductor	USPAT ; US-PG PUB; EPO; JPO; DERW ENT; IBM_T DB	2003/10/01 08:13
2	BRS	L2	830	1 and ((thermal adj treatment) with wafer)	USPAT ; US-PG PUB; EPO; JPO; DERW ENT; IBM_T DB	2003/10/01 08:30
3	BRS	L3	1	2 and (heat adj transfer adj plate)	USPAT ; US-PG PUB; EPO; JPO; DERW ENT; IBM_T DB	2003/10/01 08:26
4	BRS	L4	53	2 and (heat adj transfer)	USPAT ; US-PG PUB; EPO; JPO; DERW ENT; IBM_T DB	2003/10/01 08:30

	Comments	Error Definition	Errors
1			0
2			0
3			0
4			0

	Type	L #	Hits	Search Text	DBs	Time Stamp
5	BRS	L5	968	1 and ((thermal adj treat\$5) with wafer)	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_T DB	2003/10/01 08:39
6	BRS	L6	56	2 and (heat near2 transfer)	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_T DB	2003/10/01 08:40
7	BRS	L7	24	6 and (temperature near2 (gradient or distribution))	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_T DB	2003/10/01 11:00
8	BRS	L8	1156	1 and ((thermal near2 treat\$5) with wafer)	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_T DB	2003/10/01 08:40

	Comments	Error Definition	Errors
5			0
6			0
7			0
8			0

	Type	L #	Hits	Search Text	DBs	Time Stamp
9	BRS	L9	85	8 and (heat near2 transfer)	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_T DB	2003/10/01 08:40
10	BRS	L10	47	9 and (temperature near2 (gradient or distribution))	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_T DB	2003/10/01 08:42
11	BRS	L11	10	10 and (inclination or slope or proclivity or angle or leaning)	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_T DB	2003/10/01 08:51
12	BRS	L12	629	1 and ((wafer near2 heat\$3) with (assamblee or device or plate or element or unit)) and (inclination or slope or proclivity or angle or leaning)	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_T DB	2003/10/01 11:01

	Comments	Error Definition	Errors
9			0
10			0
11			0
12			0

	Type	L #	Hits	Search Text	DBs	Time Stamp
13	BRS	L13	703	1 and ((wafer near2 heat\$3) with (assamblee or device or plate or element or unit)) and (inclin\$5 or slope or proclivity or angle or leaning)	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_T DB	2003/10/01 08:59
14	BRS	L14	212	13 and (temperature near2 (gradient or distribution))	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_T DB	2003/10/01 09:00
15	BRS	L15	81	13 and ((surface or wafer) near2 temperature near2 (gradient or distribution))	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_T DB	2003/10/01 11:58
16	BRS	L16	60	15 and spac\$3	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_T DB	2003/10/01 09:02

	Comments	Error Definition	Errors
13			0
14			0
15			0
16			0



	Type	L #	Hits	Search Text	DBs	Time Stamp
17	BRS	L17	0	15 and (spac\$3 with (upper adj surface) with (assembl\$3 or device or plate or element or unit))	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_T DB	2003/10/01 09:05
18	BRS	L18	8	15 and (spac\$3 with (upper adj surface))	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_T DB	2003/10/01 09:05
19	BRS	L19	4	7 and (inclination or slope or proclivity or angle or leaning)	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_T DB	2003/10/01 11:01
20	BRS	L20	7	13 and ((surface or wafer) near2 temperature near2 (gradient or distribution)) and (wafer near2 gap)	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_T DB	2003/10/01 12:02

	Comments	Error Definition	Errors
17			0
18			0
19			0
20			0

	Type	L #	Hits	Search Text	DBs	Time Stamp
21	BRS	L21	24	14 and (wafer near2 gap)	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_T DB	2003/10/01 12:03

	Comments	Error Definition	Errors
21			0